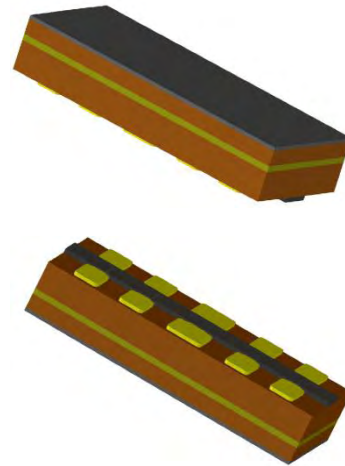


# ESD Protection Devices

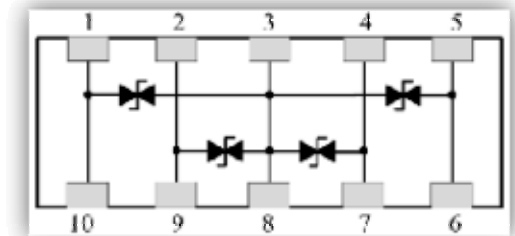
## Description

- This device is an ultra low capacitance ESD product designed to protect very high speed data interfaces. PE12A-2510 has a typical capacitance of only 0.05pf (I/O to GND), and it can be used to meet the ESD immunity requirements of IEC61000-4-2 (15KV air, 8KV contact discharge).



## Feature

- ESD protection for high speed data lines to IEC61000-4-2
- ESD contact discharge typical 8KV, max 15KV
- ESD air discharge typical 15KV, max 25KV
- Surface mount
- Extremely low capacitance
- Very low leakage current
- Fast response time
- Bi-directional ESD protection
- Lead free solder termination
- The best ESD protection for high frequency, low voltage applications



Schematic Diagram

## Application

- High Definition Multi-Media Interface (HDMI)
- Digital Visual Interface (DVI)
- Display Port Interface (DP)
- Unified Display Interface (UDI)
- Mobile Display Digital Interface (MDDI)
- Gigabit Ethernet
- USB2.0 and USB3.0
- IEEE1394 interface

## Absolute Maximum Ratings

Parameter	Symbol	Value	Unit
Maximum Contact discharge voltage Per IEC61000-4-2	---	15KV	V
Maximum Air discharge voltage Per IEC61000-4-2	---	25KV	V
Maximum Operating temperature	T <sub>OPER</sub>	-55 to +125	°C
Maximum Storage temperature	T <sub>STG</sub>	-25 to +35	°C
Maximum lead temperature for soldering during 10s	T <sub>L</sub>	260	°C

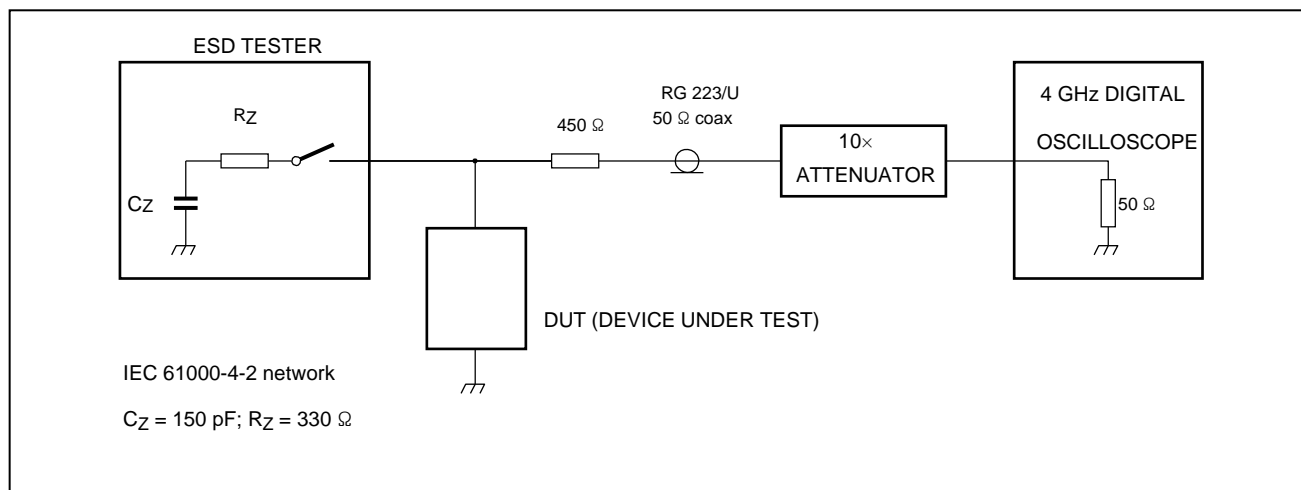
## Electrical Characteristics(T<sub>A</sub>=25°C)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Units
Rated Voltage	V <sub>R</sub>	---	---	---	12	V
Trigger voltage	V <sub>T</sub>	IEC61000-4-2 8KV contact discharge	---	300	---	V
Clamping voltage	V <sub>C</sub>	IEC61000-4-2 8KV contact discharge	---	35	---	V
Leakage current	I <sub>L</sub>	DC 12V shall be applied on component	---	0.01	0.10	uA
Capacitance	C <sub>P</sub>	V <sub>R</sub> = 0V, f = 1MHz	---	0.2	---	pF

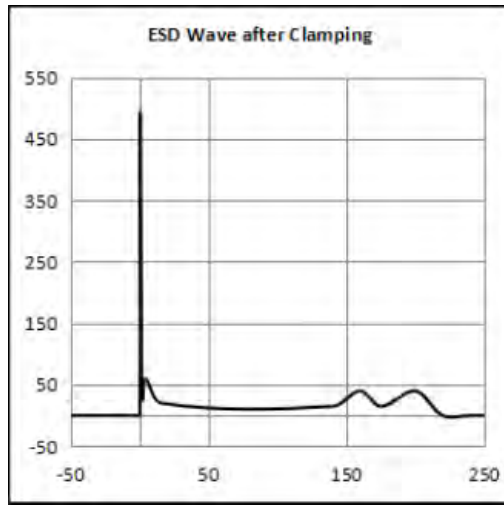
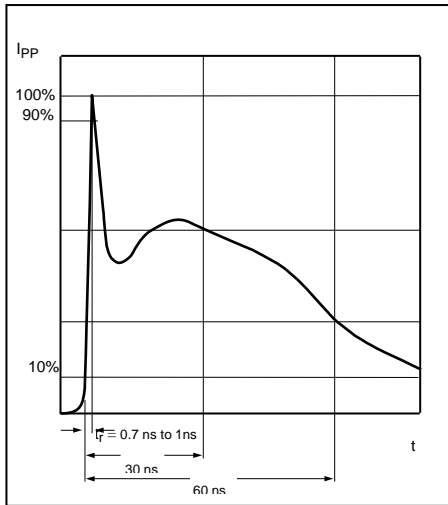
**Note:** 1 Trigger and clamping voltage are measured per IEC 61000-4-2, 8KV contact discharge method.

2 After reliability tests such as high temp storage, temp cycles, continuous ESD strike etc, the maximum leakage current is less than 10uA.

## ESD Clamping Test

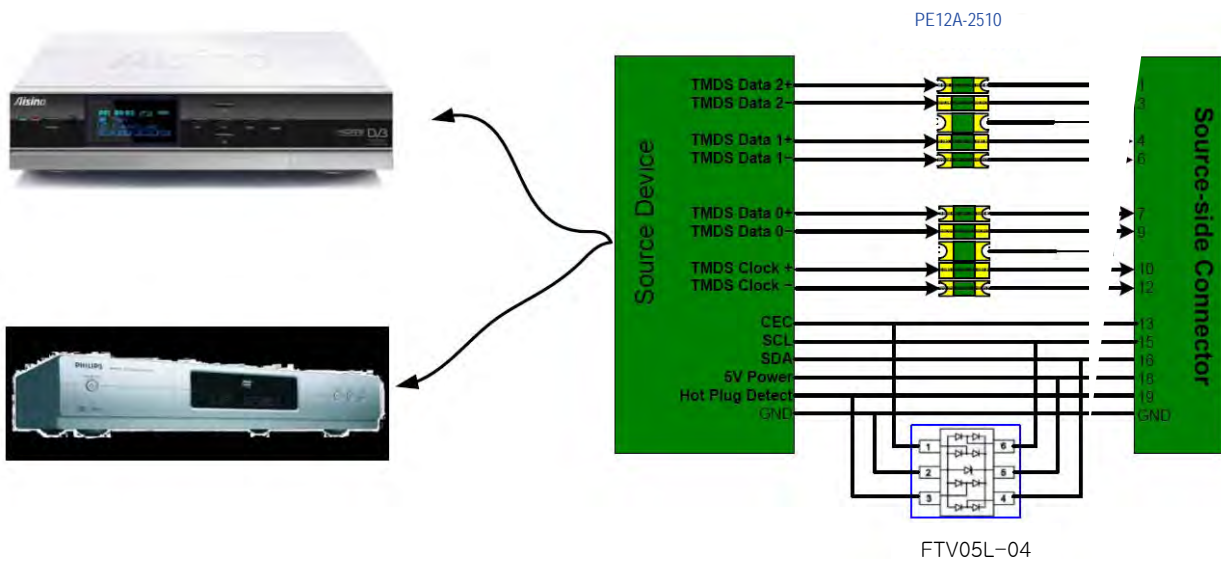


## Typical PESD clamping for +8KV pulse per IEC61000-4-2

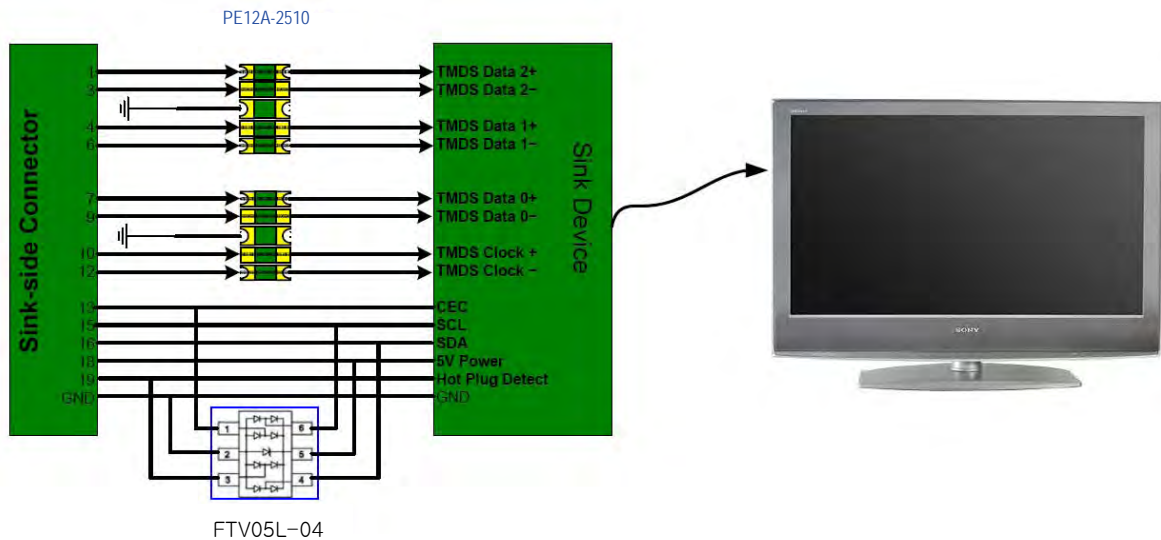


## Design Recommendations for HDMI

For HDMI Source Device

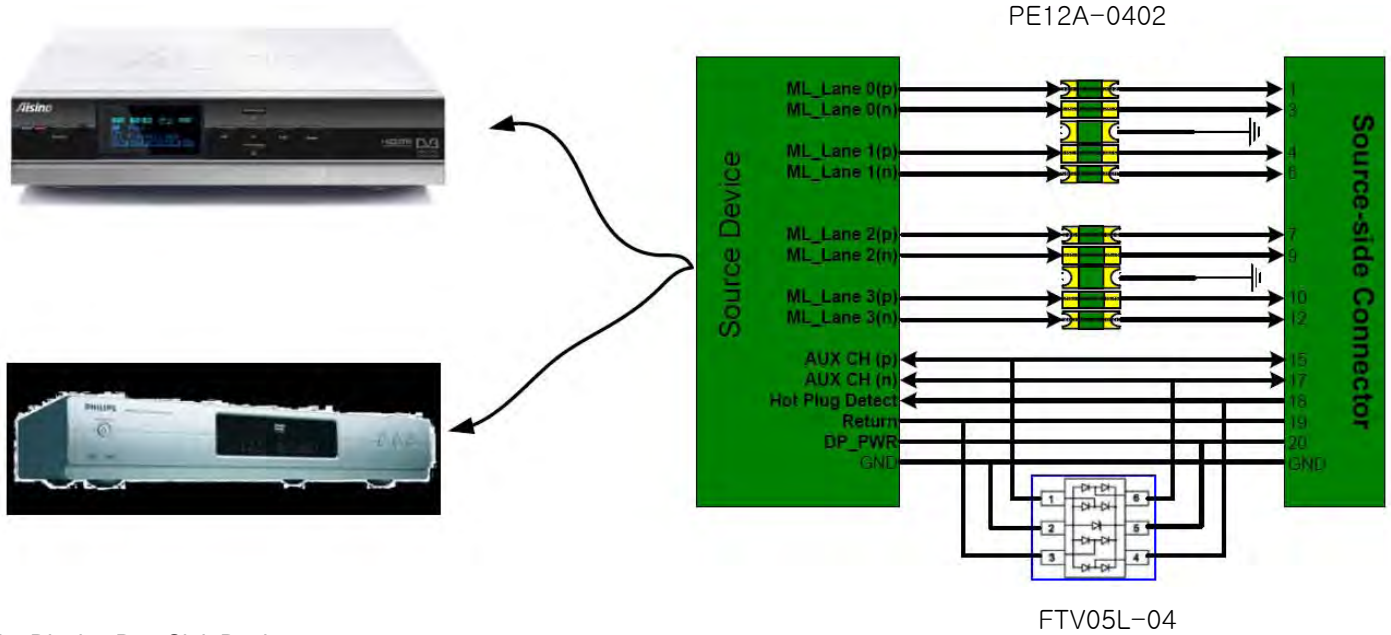


For HDMI Sink Device

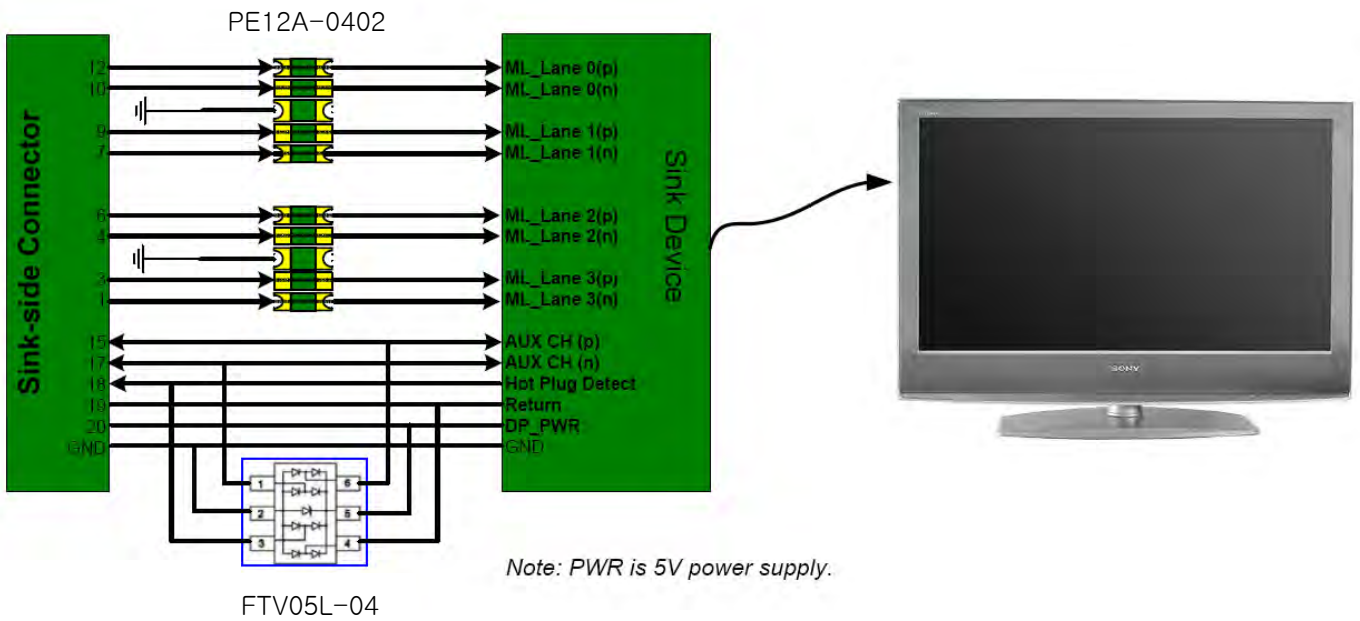


## Design Recommendations for Display Port

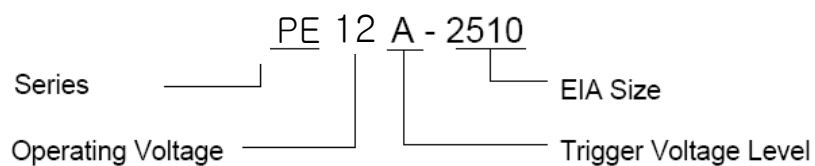
For Display Port Source Device



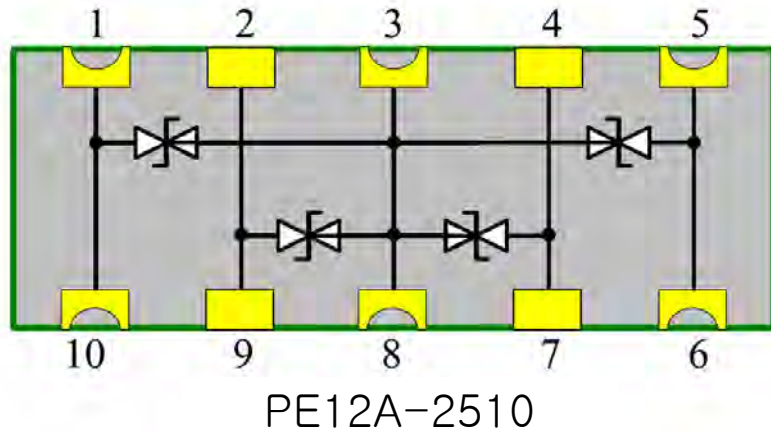
For Display Port Sink Device



## Part Numbering

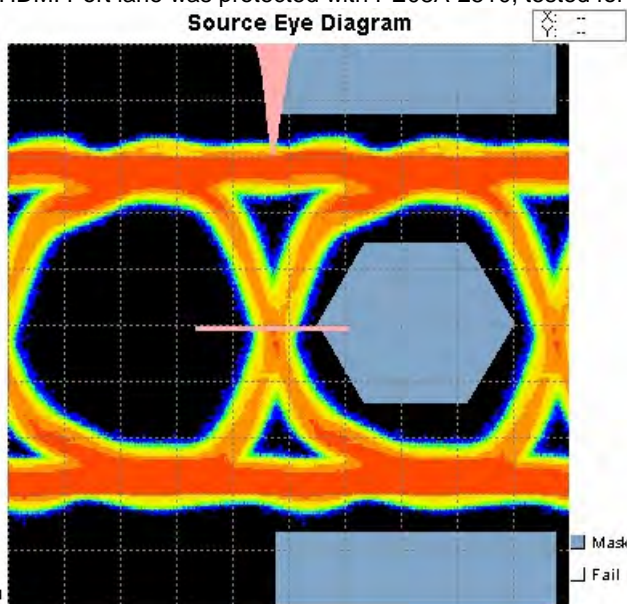


## Circuit diagram

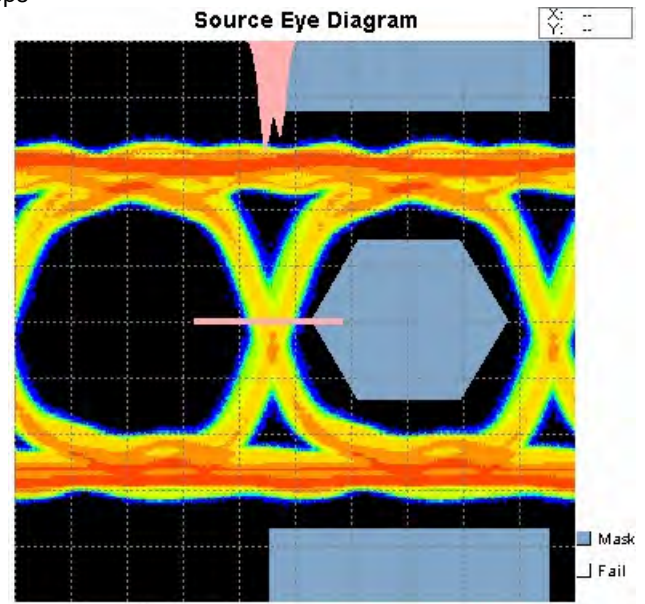


## Eye Pattern Test

HDMI Port lane was protected with PE08A-2510, tested for 2.25G bps



HDMI Port without PE12A-2510



HDMI Port with PE12A-2510

## Environmental Specifications

Operation temperature: -40~125°C

Moisture Resistance, Steady state: MIL-STD-833, Method 1004.7, 85% RH, 85 °C, 1000hrs

Thermal Shock: MIL-STD-202, Method 107G, -55°C to 150°C, 30 min cycle, 10 cycles.

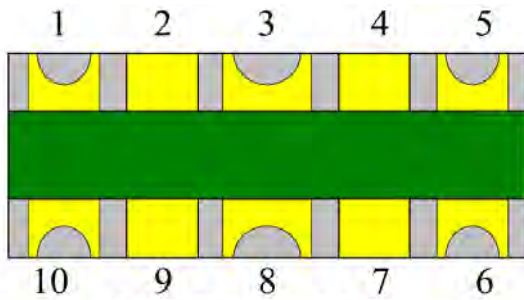
V 10HZ, 1 min. cycle, 2hrs each in X-Y-Z) STD-202F, Method 201A, (10 to 55 to

Chemical Resistance: ASTM D-543, 4hrs @40°C, 3 solutions (H<sub>2</sub>O, detergent solution, deluxer )

Solder leach resistance and terminal adhesion: Per EIA-576 test



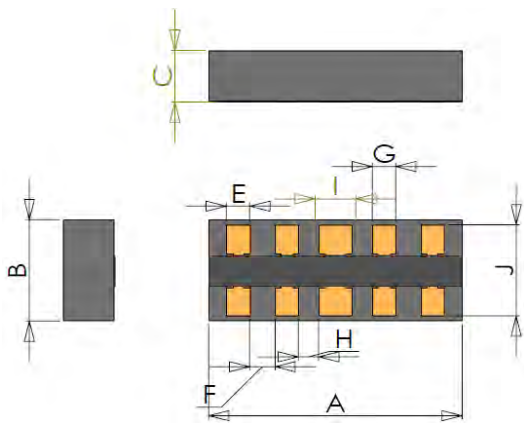
## Pin configuration



Pin	Identification
1, 2, 4, 5	Input lines
6, 7, 9, 10	Output lines
3, 8	Ground

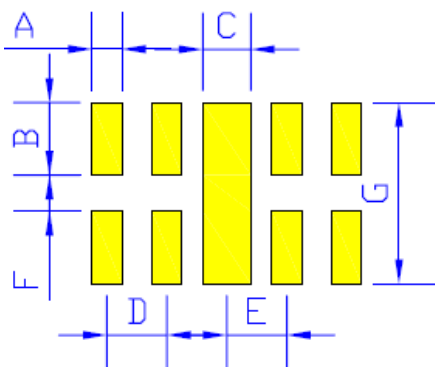
PE12A-2510

## Product Dimensions (mm)



Symbol	Dimension			Unit
	Min	Typ	Max	
A	2.40	2.50	2.60	mm
B	0.90	1.00	1.10	
C	0.40	0.50	0.60	
E	0.21	0.23	0.25	
F	0.23	0.25	0.27	
G	0.21	0.23	0.25	
H	0.18	0.20	0.22	
I	0.315	0.335	0.355	
J	0.89	0.91	0.93	

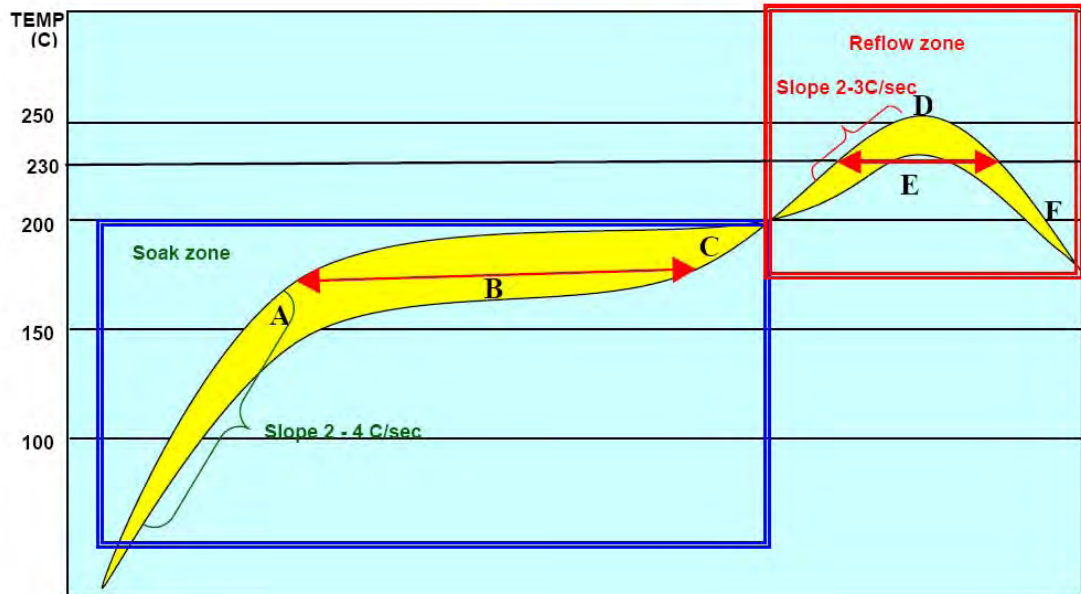
## Solder Pad Layouts



A		B		C		D		Unit
Min	Max	Min	Max	Min	Max	Min	Max	
0.20	0.30	0.55	0.65	0.35	0.45	0.45	0.55	mm
E		F		G				Unit
Min	Max	Min	Max	Min	Max			
0.45	0.55	0.25	0.35	1.4	1.6			mm

## Solder Reflow Recommendation

### PESD Solder Profile



Item	Process	Description	Reach Temp.	Time or Rate
A	Soak Start	From ambient to soak temperature and soak start	150°C - 180°C	2°C - 4°C / sec
B	Soak time	Soak time	---	60s - 120s
C	Soak end	Soak end	180°C - 200°C	---
D	Peak Temp.	From soak temperature to Peak temperature	260°C	2°C - 3°C / sec
E	Time above	Main heating time	230°C - 260°C	40s - 60s
F	Cooling	From main heating temperature to 100°C	100°C	Max. 4°C / sec

#### Notes:

1\* Peak temperature can be high to 260°C, and the recommendation time is as below

at 230°C	40s ~ 60s
at 240°C	30s ~ 40s
at 260°C	5s ~ 10s

2\* Recommended reflow methods: IR, Vapor phase oven, hot air oven, wave solder.

3\* Devices can be cleaned using standard industry methods and solvents.

4\* Component can withstand 270°C 10 sec.

5\* If reflow temperatures exceed the recommended profile, devices may not meet the performance requirements.

## Package Information

Tape & Reel: 3000pcs per reel.